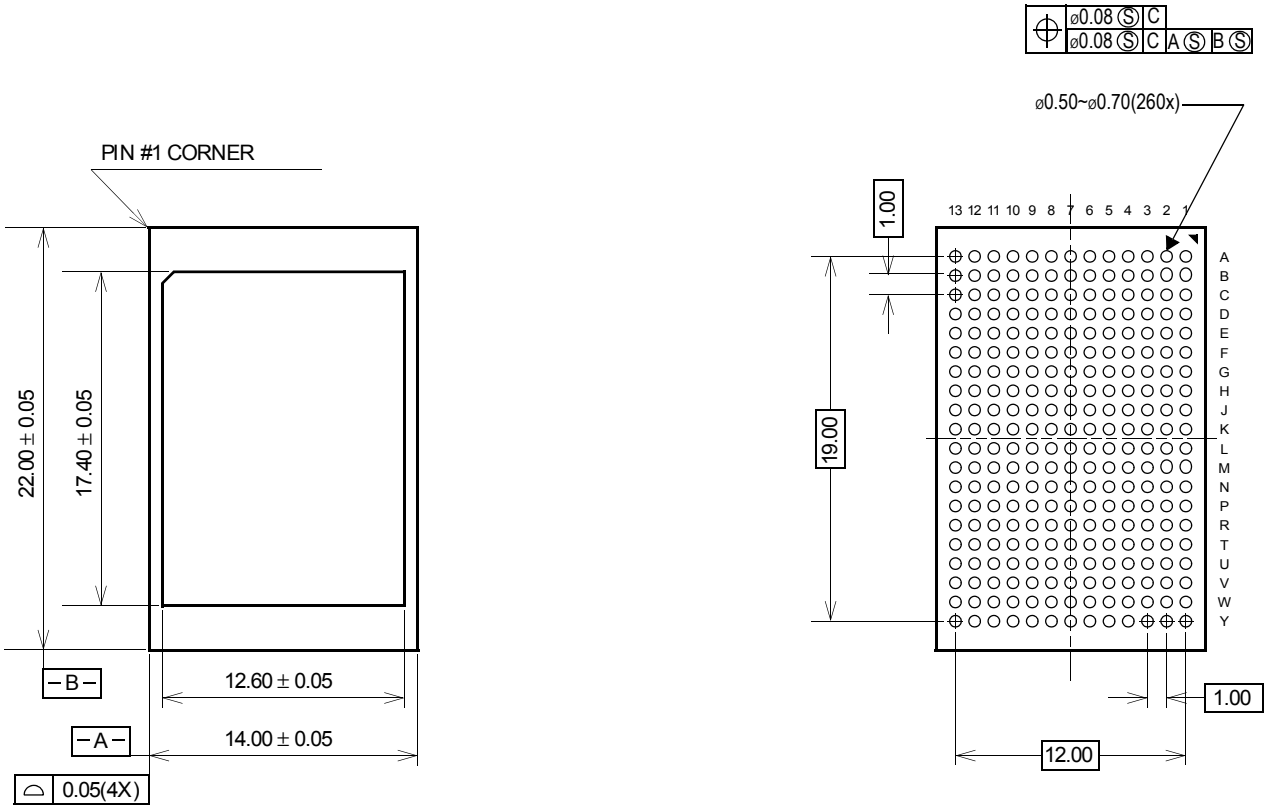
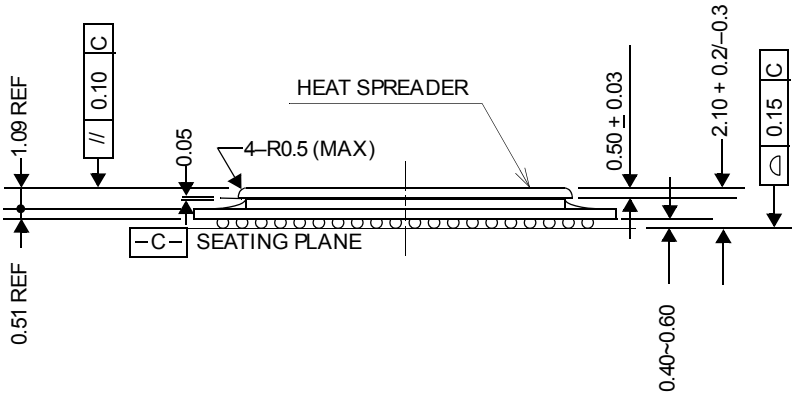
260-Pin BGA Package Drawing (Package K)





Ball Pitch:	1.00	Substrate Thickness:	0.51
Ball Diameter:	0.60	Mold Thickness:	—